



# SUA-110E8-30x-S242

鍍層厚度:

Blank : 1u"
2 : 15u"
3 : 30u"

## NOTE:

### 1.MATERIAL:

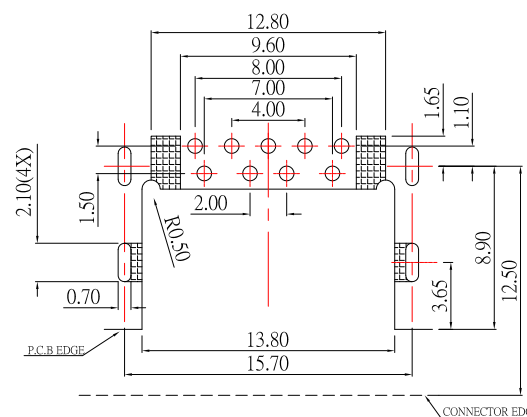
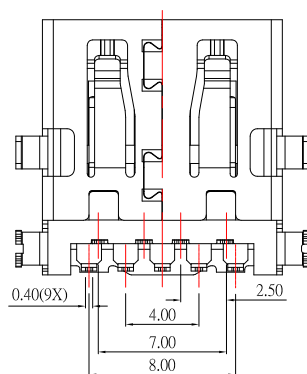
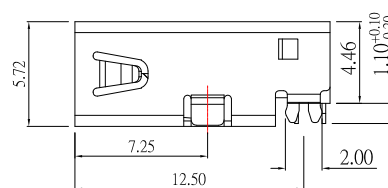
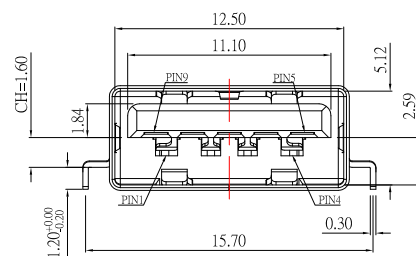
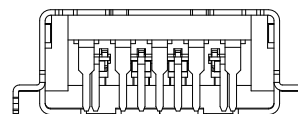
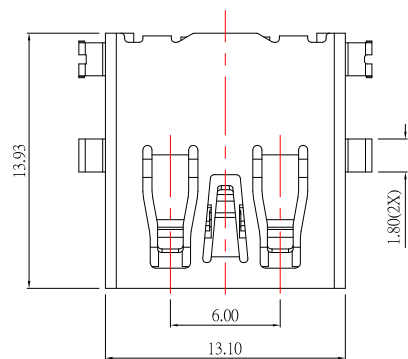
- 1.1 Housing: PBT,(UL94V-0)
- 1.2 Contact: Copper Alloy
- 1.3 Shell: SUS

### 2.Finish:

- 2.1 Contact: Plated Gold in Mating Area ;  
Tin Plated on Solder Balls ;  
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

### 3.SPECIFICATION:

- 3.1 Current Rate: 1.5 A
- 3.2 insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 500V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: -55°C ~ +85°C
- 3.6 Insertion Force: 35 N
- 3.7 Extraction Force: 10 N



RECOMMENDED PCB LAYOUT  
(TOP VIEW)

**CONTACT** 建倚科技股份有限公司  
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED:  
Up to 5 ±0.2  
Above 5 ~ 15 ±0.3  
Above 15 ~ 30 ±0.4  
Above 30 ~ 50 ±0.5  
Angle ±0.3

3RD. ANGEL'S



UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	08/16/18		MODLE	USB 3.0 A/F 沉板H:4.46 DIP, 無捲邊
CHECKED BY:	DATE	SCALE	DWG NO.	SUA-110E8-30x-S242
Jacky Chen	08/16/18	1 : 1	PART NO.	SUA-110E8-30x-S242
APPROVED BY:	DATE	SHEET NO.	1 of 1	
Tony Kao	08/16/18			

ITEM NO.	DESCRIPTION	DRAWN	DATE